

DB3X313N

Silicon epitaxial planar type

For small current rectification

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4N

■ Basic Part Number

Dual DB2J313 (Common Cathode)

■ Packaging

DB3X313N0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	Single	200	mA
	Double *1		
Peak forward current	Single	300	mA
	Double *1		
Non-repetitive peak reverse surge voltage *2	Single	1.0	A
	Double *1		
Junction temperature	T_j	125	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-40 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Value of each diode in double diodes used.

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

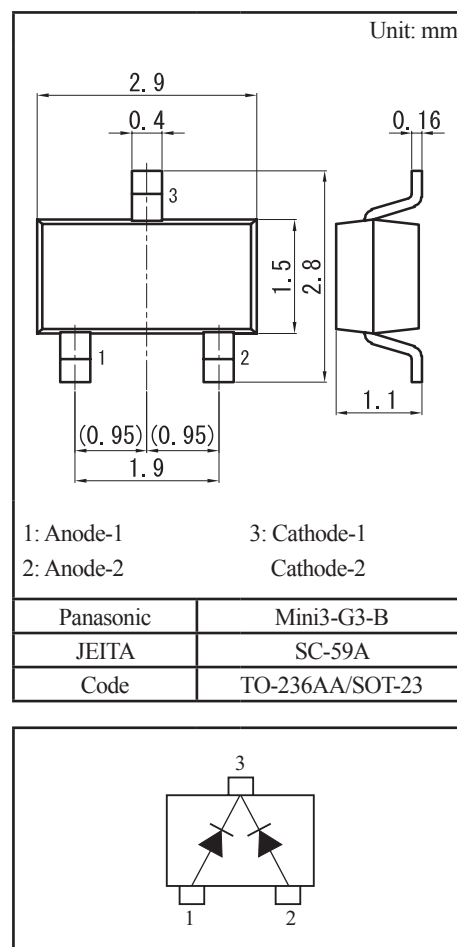
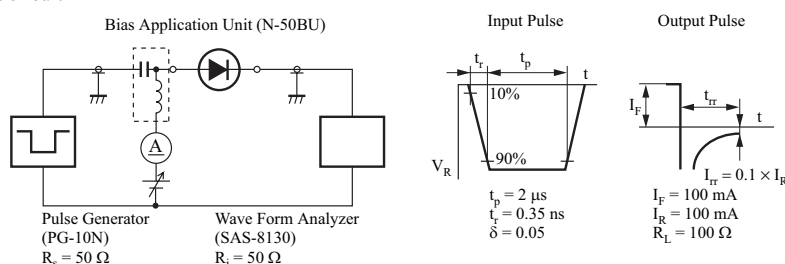
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μA
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.8		pF
Reverse recovery time *1	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{tr} = 0.1 \times I_R, R_L = 100 \Omega$		1.5		ns

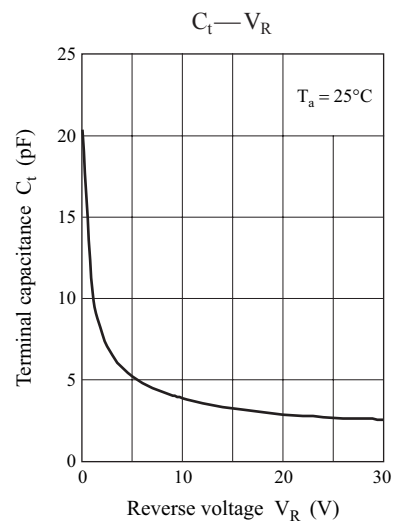
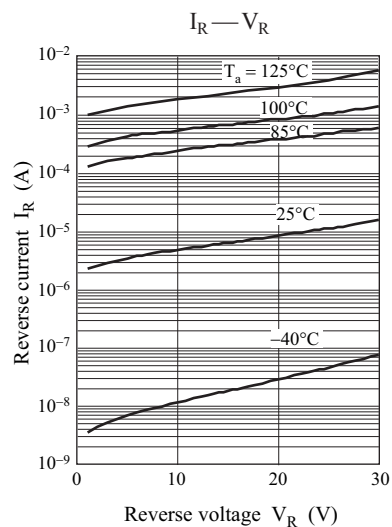
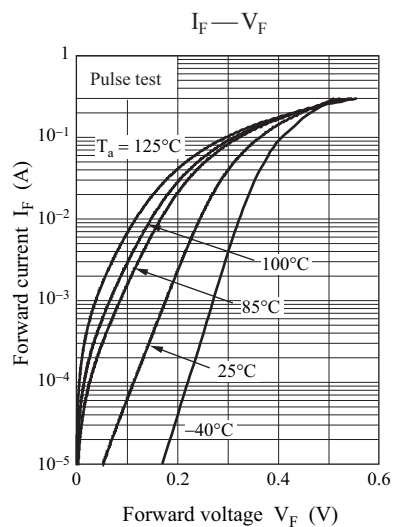
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 1 GHz

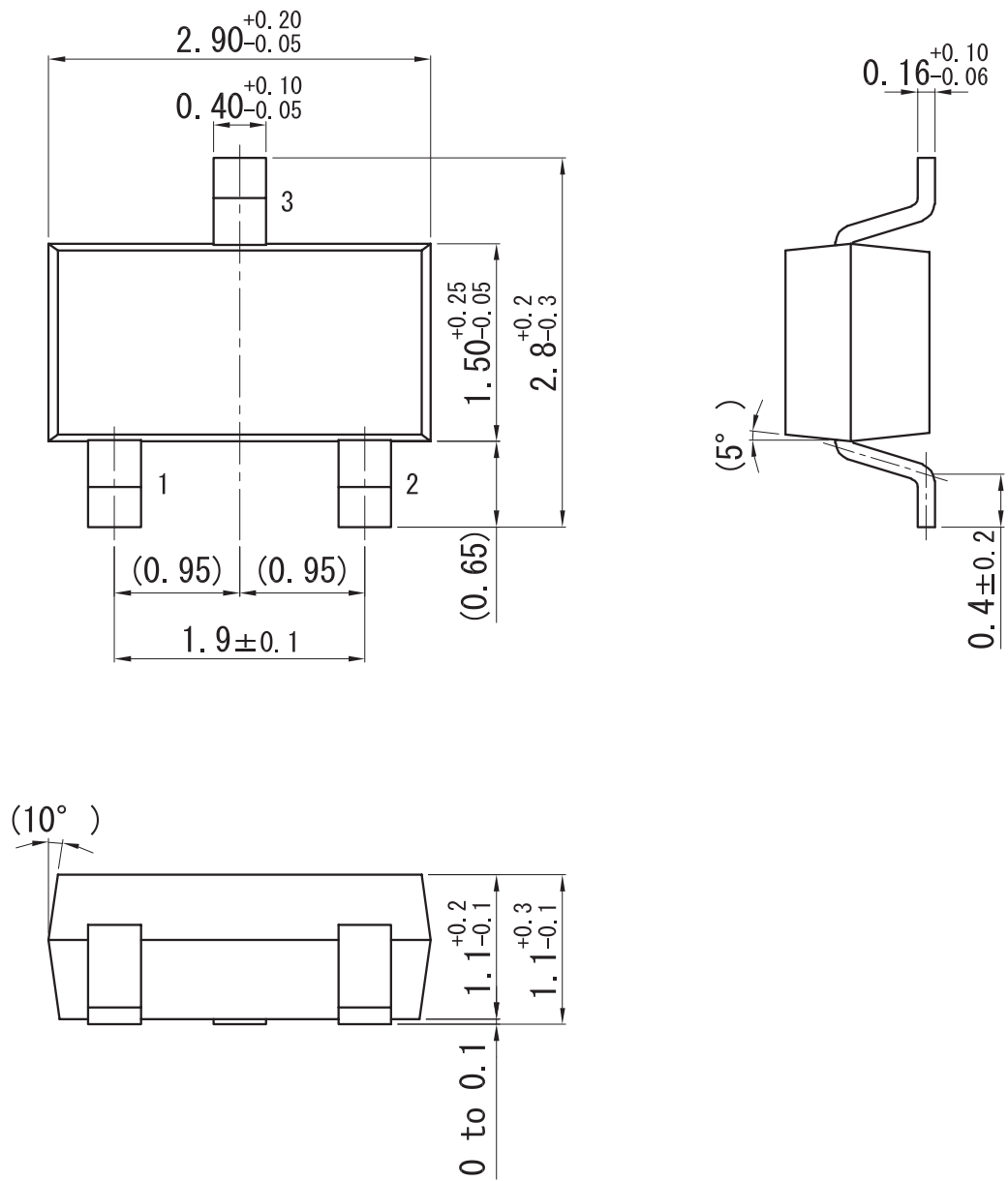
*1: t_{rr} measurement circuit



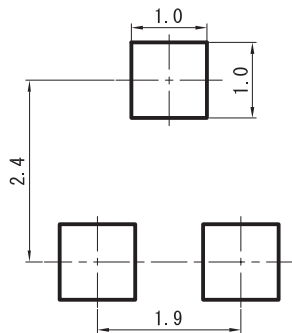


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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